



APR-03-003

February 27, 2004

To: Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/742,306 12/19/03 |  
| Carl Chng Han Shen et al. |  
| VARIOUS STRUCTURE/HEIGHT BUMPS FOR |  
| WAFER LEVEL-CHIP SCALE PACKAGE |  
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#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on March \, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Step B Ack 3/1/04

U.S. Patent 6,486,054 to Fan et al., "Method to Achieve Robust Solder Bump Height," describes a method to achieve robust solder bump height.

U.S. Patent 6,184,581 to Cornell et al., "Solder Bump Input/Output Pad for a Surface Mount Circuit Device," describes a solder bump input/output pad for a surface mount circuit device with adjacent input/output pads also having triangular shapes or diamond shapes.

U.S. Patent 5,926,731 to Coapman et al., "Method for Controlling Solder Bump Shape and Stand-off Height," describes a method for controlling solder bump shape and stand-off height.

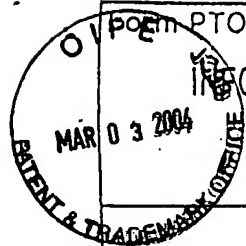
U.S. Patent 6,297,551 to Dudderar et al., "Integrated Circuit Packages with Improved EMI Characteristics," describes integrated circuit packages with improved EMI characteristics.

U.S. Patent 4,430,690 to Chance et al., "Low Inductance MLC Capacitor with Metal Impregnation and Solder Bar Contact," describes a low inductance MLC capacitor with metal impregnation and solder bar contact.

Sincerely,

A handwritten signature in black ink, appearing to read 'S. B. Ackerman', with a stylized flourish at the end.

Stephen B. Ackerman,  
Reg. No. 37761



PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)	Docket Number (Optional) <b>APS-03-003</b>	Application Number <b>10/742,306</b>
	Applicant <b>Carl Chng Han Shen et al.</b>	
	Filing Date <b>12/19/03</b>	Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE
	6486054	11/26/02	Fan et al.	438	613	1/28/02
	6184581	2/6/01	Cornell et al.	257	737	11/24/97
	5926731	7/20/99	Coapman et al.	438	613	7/2/97
	6297551	10/2/01	Dudderar et al.	257	723	9/22/99
	4430690	2/7/84	Chance et al.	361	321	10/7/82

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)


EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.